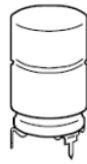


# Aluminium electrolytic capacitor

# Material Data Sheet

<b>Product Class</b>	Hybrid polymer soldering star vertical	
<b>Date</b>	11.05.2022	
IMDS ID if available		
<b>Version</b>	03	

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
<b>Active Part</b>	Light Metals	1B	Aluminium	100	7429-90-5	32	
	Acids, Bases, Salts	6F	Sulfolane	35	126-33-0	19.7	
	Acids, Bases, Salts	6F	Ethylene glycol	55	107-21-1		
	Acids, Bases, Salts	6F	Others *)	10	-		
	Thermoplastics	2A	Polypropylene	100	9003-07-0	0.1	
	Paper, Cardboard	5C	Cellulose	100	9004-34-6	4.5	
<b>Encapsulation</b>	Light Metals	1B	Aluminium	100	7429-90-5	22.8	
	Paper, Cardboard	5C	Cellulose	56	9004-34-6	4.8	
	Duromer	2D	Phenolic plastic	44	-		
	Elastomer	2B	EPDM rubber	41,5	25038-36-2	3.1	
	Inorganic, solid	4A	Silicon dioxide	13	7631-86-9		
	Inorganic, solid	4A	Kaolinite	28,5	1318-74-7		
	Lubricant	6B	Paraffin	10,5	8012-95-1		
	-	-	Others *)	6,5	-		
	Thermoplastics	2A	PTFE	100	9002-84-0	0.5	
	Thermoplastics	2A	Polyethylene terephthalate or without insulation	90	25038-59-9	5.6	
		Others *)	10	-			
<b>Termination</b>	Iron and steel	1A	Iron	99	7439-89-6	5.3	
			Others *)	1	-		
	Heavy Metals	1C	Copper	100	7440-50-8	1	
	Heavy Metals	1C	Tin	100	7440-31-5	0.6	
<b>Sum in total:</b>						100	

sizes D x L [ mm ]	weight range [ g ]	part numbers
14 x 25	6.1	B40700
14 x 30	7.3	B40720
16 x 25	7.7	B40740/B40750
16 x 30	9.1	
18 x 25	9.5	
18 x 30	11	

<b>Not Part of a Product Class</b>		
<b>Contact</b>	Ivett Bálint	<b>Important remarks:</b> 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated. 2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.
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*) others: (not declarable or prohibited substances acc. GADSL)		
**) typical mass percentage of substance		

**The products set forth herein are "RoHS-compatible".** RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8<sup>th</sup>, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

**RoHS - Exemptions for the Product Class / Product according to Annex III: (  valid  not valid )**

- no exemptions;**
- Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;
- Exemption 6 (b): Lead as an alloying element in aluminum containing up to 0,4 % lead by weight;
- Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;
- Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);
- Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;
- Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
- Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;
- Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;
- Other Exemption than above .....